

[illegible]

/ Descriptions

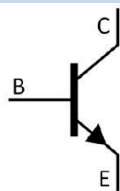
TO-252                  NPN

/ Features

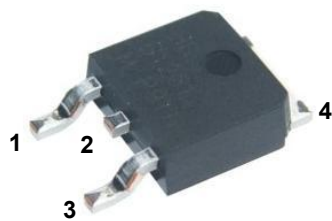
AEC-Q101

/ Applications

/ Equivalent Circuit



/ Pinning



/ h<sub>FE</sub> Classifications & Marking

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/ Electrical Characteristic Curve

Fig. 1 - Static Characteristics

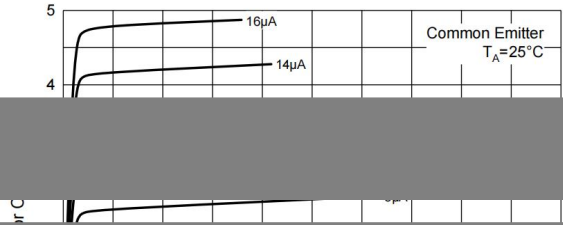


Fig. 2 - DC Current Gain Characteristics

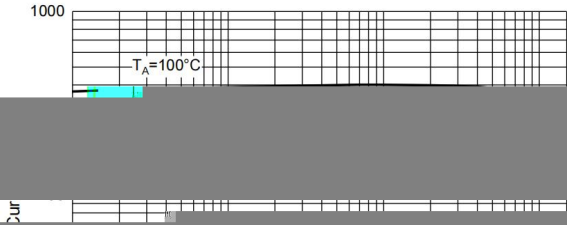


Fig. 3 - Collector-Emitter Saturation



Fig. 5 - Base-Emitter Voltage Characteristics

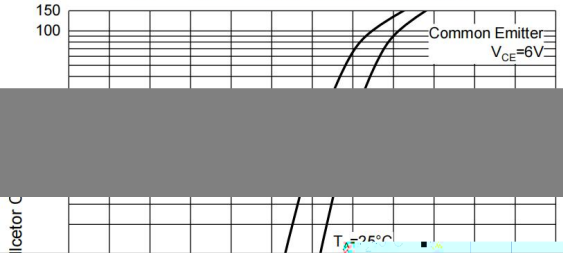
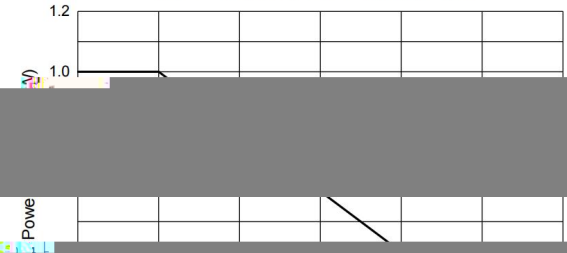
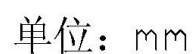


Fig. 6 - Collector Power Derating Curve

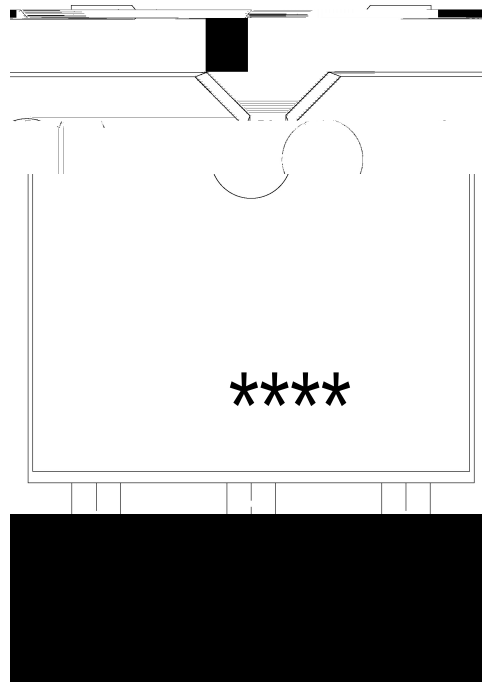




| Dimensions in millimeters |      |        |      | Dimensions in millimeters |      |        |     |
|---------------------------|------|--------|------|---------------------------|------|--------|-----|
| En                        | Max  | Symbol | Min  | Max                       |      | Symbol | Max |
| 220                       | 240  | L1     | 5.95 | 6.25                      |      | A1     | 2   |
| 0.95                      | 1.25 | e1     | 2.24 | 2.34                      |      | P1     |     |
| 0.70                      | 0.90 | e2     | 4.43 | 4.73                      |      | b=     |     |
| 0.45                      | 0.55 | L1     | 9.85 | 10.35                     |      | b1     |     |
| 0.00                      | 0.45 |        | 0.45 | 0.60                      | 0.72 | 0.60   |     |
| 0.90                      |      | D      | 6.45 | 6.75                      | 13   | 0.60   |     |
| 0.10                      |      | D1     | 5.10 | 5.50                      | K    | 0.00   |     |

TJ-252

/ Marking Instructions

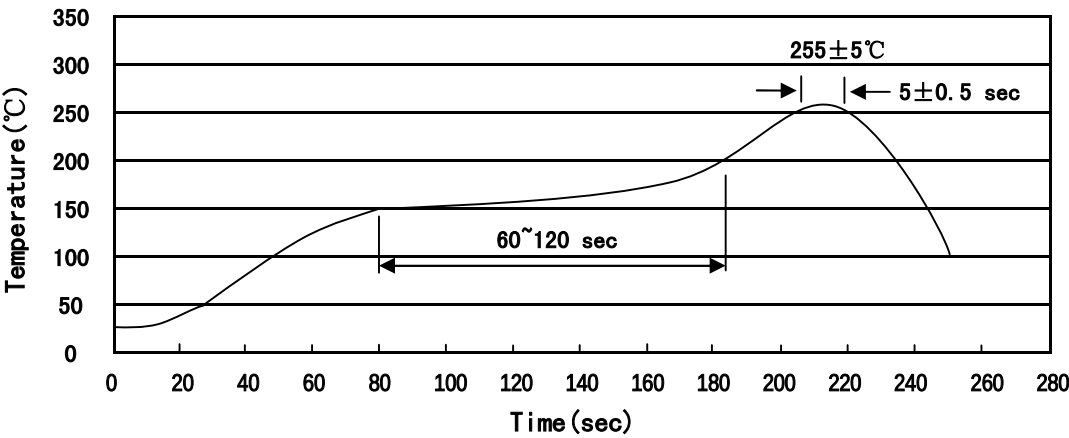


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(     ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 、预热温度     ~     °C，时间     ~     °C
- 、峰值温度     ± °C，时间持续为     ±     °C     ±     °C
- 、焊接制程冷却速度为     ~     °C     °C

/ Resistance to Soldering Heat Test Conditions

温度：     ± °C     时间：     ±     °C

/ Packaging SPEC.

卷盘包装

|        | Units/Reel<br>只/卷盘 | Reels/Inner Box<br>卷盘/盒 | Units/Inner Box<br>只/盒 | Inner Boxes/Outer Box<br>盒/箱 | Units/Outer Box<br>只/箱 | Reel    | Inner Box  | Outer Box   |
|--------|--------------------|-------------------------|------------------------|------------------------------|------------------------|---------|------------|-------------|
| TO-252 | 2,500              | 2                       | 5,000                  | 6                            | 30,000                 | 13" ×16 | 360×360×50 | 380×335×366 |

套管包装

|            | Units/Tube<br>只/套管 | Tubes/Inner Box<br>套管/盒 | Units/Inner Box<br>只/盒 | Inner Boxes/Outer Box<br>盒/箱 | Units/Outer Box<br>只/箱 | Tube          | Inner Box  | Outer Box   |
|------------|--------------------|-------------------------|------------------------|------------------------------|------------------------|---------------|------------|-------------|
| TO-251/252 | 75                 | 48                      | 3,600                  | 5                            | 18,000                 | 526×20.5×5.25 | 555×164×50 | 575×290×180 |

/ Notices